



MACOM Technology Solutions Inc.,  
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### **EU RoHS Directive Statement**

MACOM Technology Solutions is committed to compliance with the EU RoHS Directive 2011/65/EU, on the restriction of the use of certain hazardous substances in electrical and electronic equipment (“EEE”), along with associated Delegated Directives and amendments.

The EU RoHS Directive stipulates that EEE must not contain above 0.1% (except for cadmium which is limited to 0.01%) by weight of homogeneous material of the restricted substances. However, the legislation includes certain exemptions, where a restricted substance can be used above the threshold in certain applications. Electronic equipment for use in aerospace & defence applications is excluded from the scope of the legislation.

MACOM products are considered to be components under the Directive. Therefore, the provisions regarding CE Marking, EU declaration of Conformity, and internal production control, as stipulated in the Directive are not applicable.

Some MACOM products use the following valid exemptions regarding the use of lead;

- 6(a)-1: Lead as an alloying element in steel for machining purposes containing up to 0.35% lead by weight and in batch hot dip galvanised steel components containing up to 0.2% lead by weight
- 6(c): Copper alloy containing up to 4 % lead by weight
- 7(a): Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
- 7(c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
- 15: Lead in solders to complete a viable electrical connection between the semiconductor die and carrier within integrated circuit flip chip packages where at least one of the following criteria applies:
  - a semiconductor technology node of 90 nm or larger;
  - a single die of 300 mm<sup>2</sup> or larger in any semiconductor technology node;
  - stacked die packages with die of 300 mm<sup>2</sup> or larger, or silicon interposers of 300 mm<sup>2</sup> or larger

For more specific information, please contact [product\\_compliance@macom.com](mailto:product_compliance@macom.com).

Regards,  
Therese Deane  
Director, Compliance & Quality Systems